metals

Correction

Correction: Zhang et al. Towards Selective Laser Melting of High-Density Tungsten. *Metals* 2023, *13*, 1431

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Following publication, it has been confirmed that authors cited one reference [46] that has been retracted prior to the publishing of this paper [1]. Adhering to our standard procedure, the Editorial Board conducted an investigation and determined that reference [46] should be removed from the reference list and its citation replaced with reference [20] through the main text. Corrections have been made accordingly in the main text of the published paper and the reference list.

The authors state that the scientific conclusions are unaffected. This correction was approved by the Academic Editor. The original publication has also been updated.

Reference

1. Zhang, H.; Wang, D.; Li, X.; Yin, F.; Zhang, L.; Li, X.; Qu, X. Towards Selective Laser Melting of High-Density Tungsten. *Metals* **2023**, *13*, 1431. [CrossRef]

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